

Dual Channel Power Driver

FEATURES

- Two independent Drivers
- 1.5A Totem Pole Outputs
- Inverting and Non-Inverting Inputs
- 40ns Rise and Fall into 1000pF
- High-Speed, Power MOSFET Compatible
- Low Cross-Conduction Current Spike
- Analog Shutdown with Optional Latch
- Low Quiescent Current
- 5V to 40V Operation
- Thermal Shutdown Protection
- 16-Pin Dual-In-Line Package
- 20-Pin PLCC and CLCC Package

DESCRIPTION

The UC1707 family of power drivers is made with a high-speed Schottky process to interface between low-level control functions and high-power switching devices - particularly power MOSFETs. These devices contain two independent channels, each of which can be activated by either a high or low input logic level signal. Each output can source or sink up to 1.5A as long as power dissipation limits are not exceeded.

Although each output can be activated independently with its own inputs, it can be forced low in common through the action either of a digital high signal at the Shutdown terminal or a differential low-level analog signal. The Shutdown command from either source can either be latching or not, depending on the status of the Latch Disable pin.

Supply voltage for both VIN and VC can independently range from 5V to 40V.

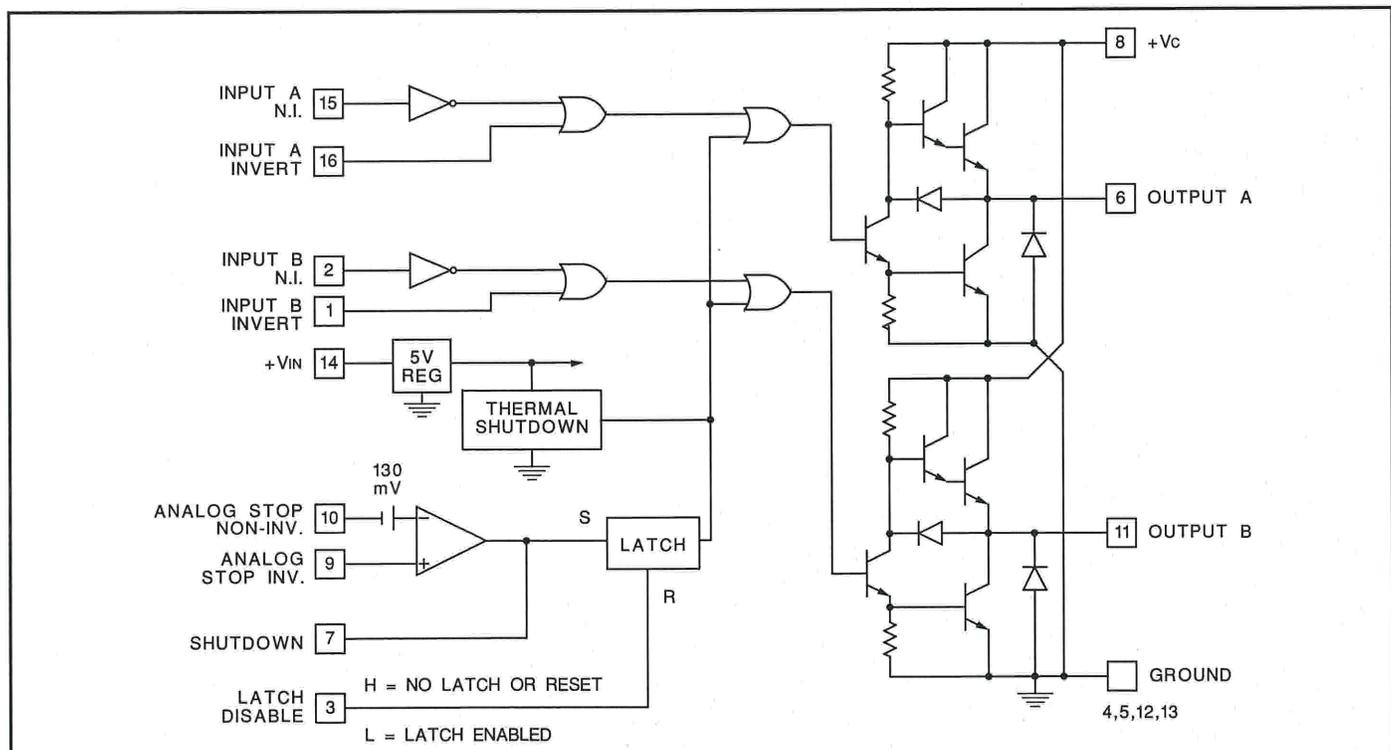
These devices are available in two-watt plastic "bat-wing" DIP for operation over a 0°C to 70°C temperature range and, with reduced power, in a hermetically sealed cerdip for -55°C to +125°C operation. Also available in surface mount DW, Q, L packages.

TRUTH TABLE (Each Channel)

INV.	N.I.	OUT
H	H	L
L	H	H
H	L	L
L	L	L

$\overline{\text{OUT}} = \overline{\text{INV}}$ and N.I.
 $\overline{\text{OUT}} = \text{INV}$ or N.I.

BLOCK DIAGRAM



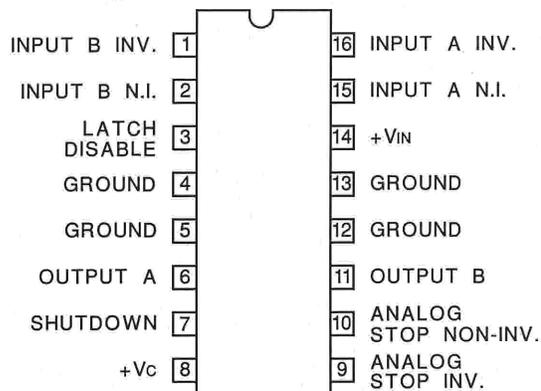
ABSOLUTE MAXIMUM RATINGS

Supply Voltage, VIN, N/J-Pkg	40V
Collector Supply Voltage, VC, N/J-Pkg	40V
Output Current (Each Output, Source or Sink) Steady-State, N/J-Pkg	±500mA
Peak Transient	
N-Pkg	±1.5A
J-Pkg	±1.0A
Capacitive Discharge Energy	
N-Pkg	20mJ
J-Pkg	15mJ
Digital Inputs (See Note), N/J-Pkg	5.5V
Analog Stop Inputs, N/J-Pkg	VIN
Power Dissipation at TA = 25°C (See Note)	
N-Pkg	2W
J-Pkg	1W
Power Dissipation at T (Leads/Case) = 25°C (See Note)	
N-Pkg	5W
J-Pkg	2W
Operating Temperature Range	-55°C to +125°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10 Seconds)	300°C

Note: All voltages are with respect to the four ground pins which must be connected together. All currents are positive into, negative out of the specified terminal. Digital Drive can exceed 5.5V if input current is limited to 10mA. Consult Packaging section of Databook for thermal limitations and considerations of package.

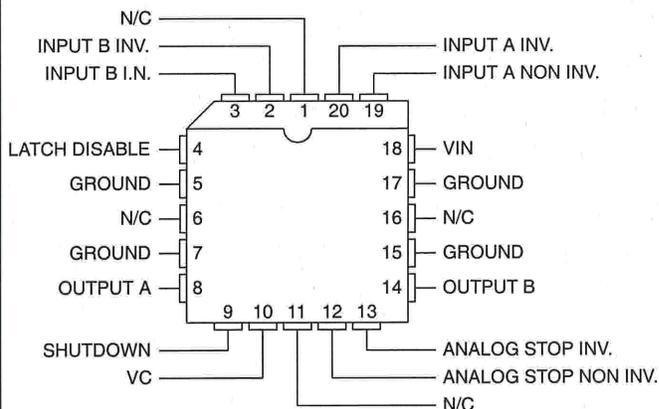
CONNECTION DIAGRAMS

DIL-16, SOIC-16 (TOP VIEW) J or N Package,



Note: All four ground pins must be connected to a common ground.

PLCC-20, LCC-20 (TOP VIEW) Q, L Packages



ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$ for the UC1707, -25°C to $+85^\circ\text{C}$ for the UC2707 and 0°C to $+70^\circ\text{C}$ for the UC3707; $V_{IN} = V_C = 20\text{V}$. $T_A = T_J$.

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
V_{IN} Supply Current	$V_{IN} = 40\text{V}$		12	15	mA
V_C Supply Current	$V_C = 40\text{V}$, Outputs Low		5.2	7.5	mA
V_C Leakage Current	$V_{IN} = 0$, $V_C = 30\text{V}$, No Load		.05	0.1	mA
Digital Input Low Level				0.8	V
Digital Input High Level		2.2			V
Input Current	$V_I = 0$		-0.06	-1.0	mA
Input Leakage	$V_I = 5\text{V}$.05	0.1	mA
Output High Sat., $V_C - V_O$	$I_O = -50\text{mA}$			2.0	V
	$I_O = -500\text{mA}$			2.5	V
Output Low Sat., V_O	$I_O = -50\text{mA}$			0.4	V
	$I_O = -500\text{mA}$			2.5	V
Analog Threshold	$V_{CM} = 0$ to 15V	100	130	160	mV
Input Bias Current	$V_{CM} = 0$		-10	-20	μA
Thermal Shutdown			155		$^\circ\text{C}$
Shutdown Threshold	Pin 7 Input	0.4	1.0	2.2	V
Latch Disable Threshold	Pin 3 Input	0.8	1.2	2.2	V

TYPICAL SWITCHING CHARACTERISTICS: $V_{IN} = V_C = 20\text{V}$, $T_A = 25^\circ\text{C}$. Delays measured to 10% output change.

PARAMETERS	TEST CONDITIONS	OUTPUT CL =			UNITS
		open	1.0	2.2	
From Inv. Input to Output					
Rise Time Delay		40	50	60	ns
10% to 90% Rise		25	40	50	ns
Fall Time Delay		30	40	50	ns
90% to 10% Fall		25	40	50	ns
From N.I. Input to Output					
Rise Time Delay		30	40	50	ns
10% to 90% Rise		25	40	50	ns
Fall Time Delay		45	55	65	ns
90% to 10% Fall		25	40	50	ns
V_C Cross-Conduction	Output Rise	25			ns
Current Spike Duration	Output Fall	0			ns
Analog Shutdown Delay	Stop non-Inv. = 0V	180			ns
	Stop Inv. = 0 to 0.5V	180			ns
Digital Shutdown Delay	2V Input on Pin 7	50			ns

SIMPLIFIED INTERNAL CIRCUITRY

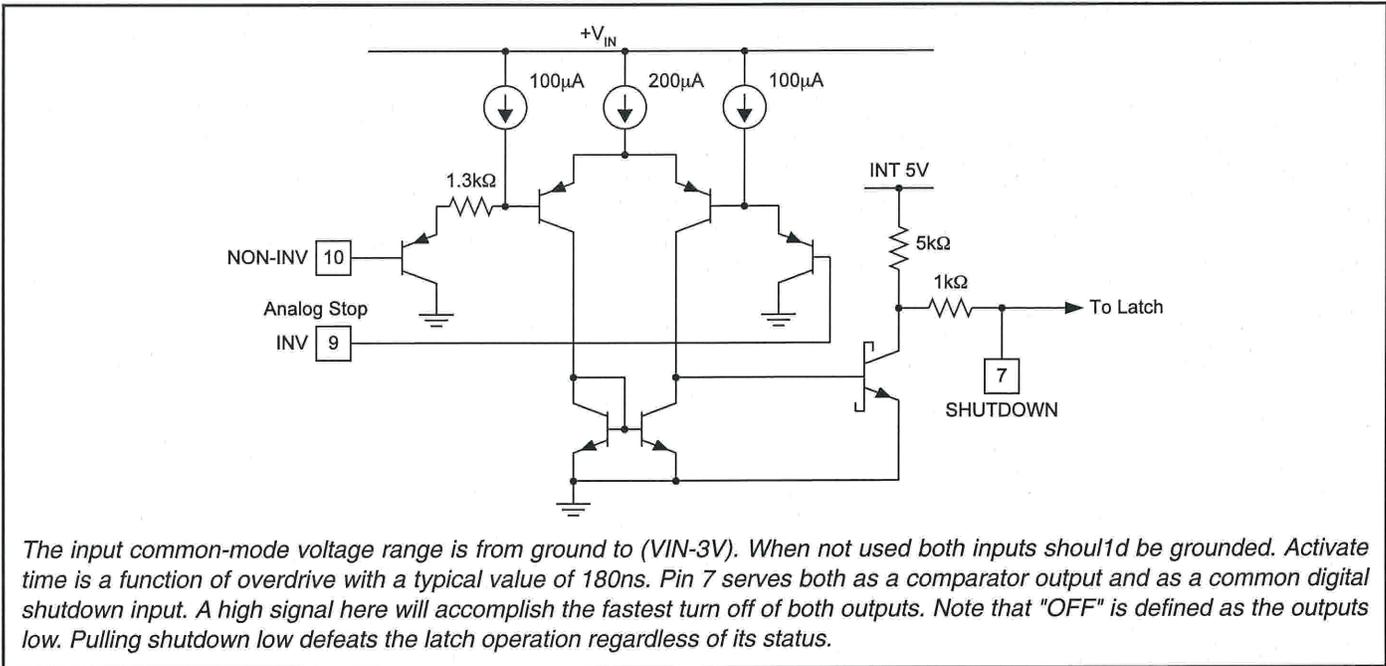


Figure 1. Typical digital input gate.

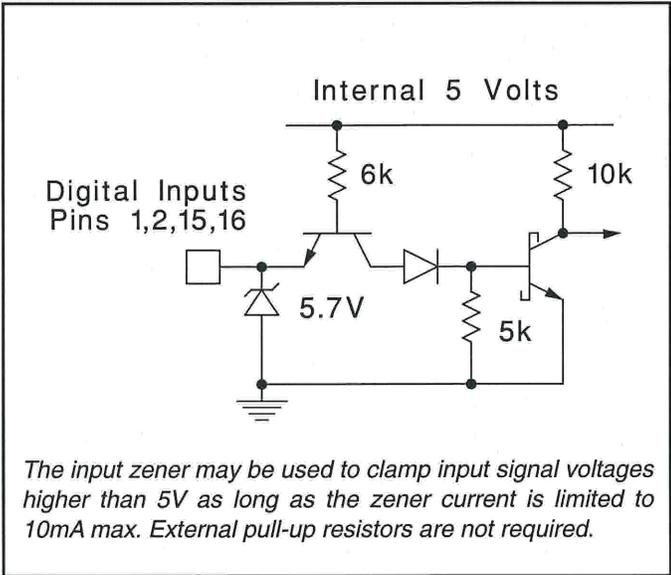


Figure 2. Typical digital input gate.

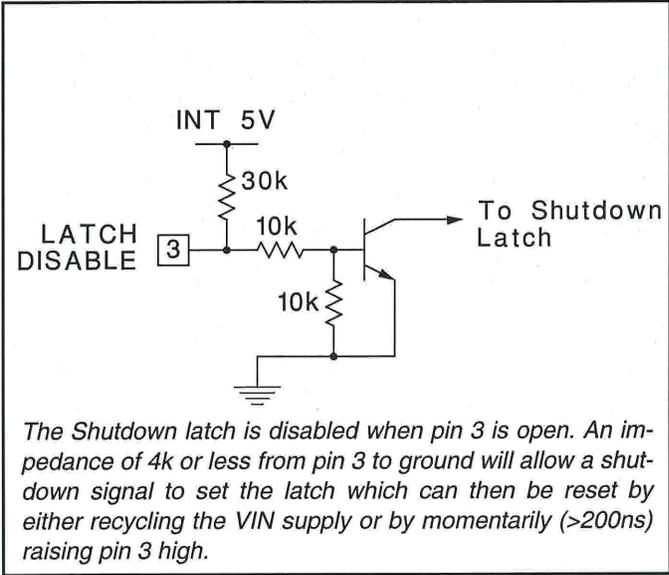


Figure 3. Latch disable.

SIMPLIFIED INTERNAL CIRCUITRY (cont.)

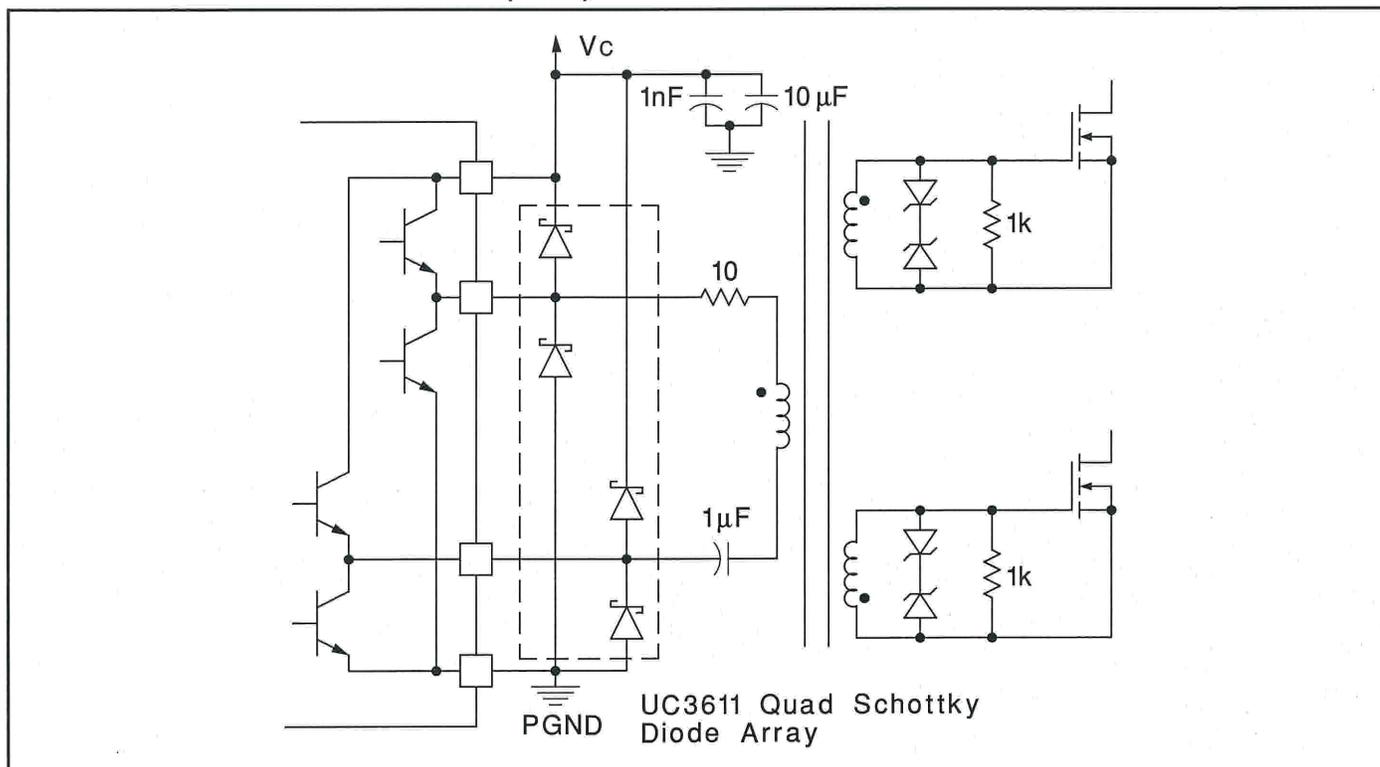
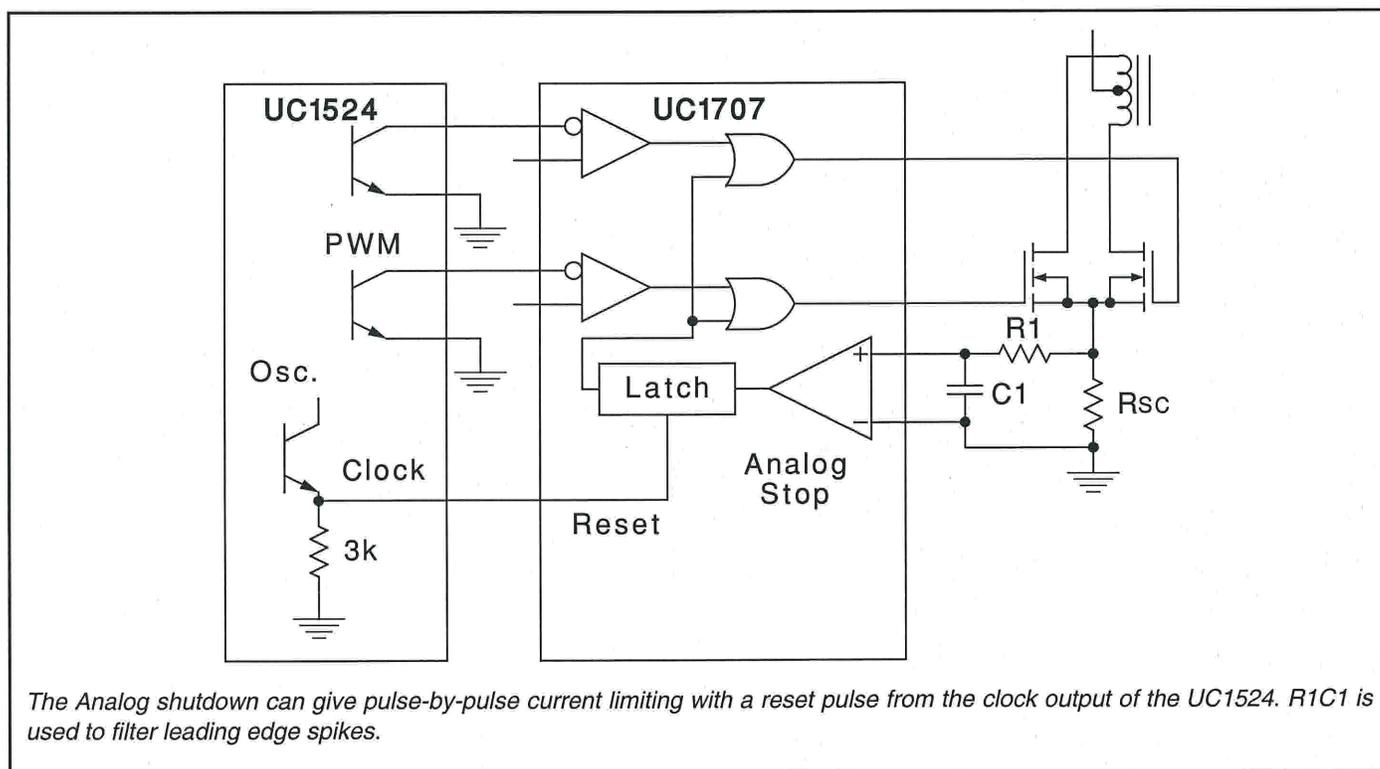


Figure 4. Transformer coupled push-pull MOSFET drive circuit.



The Analog shutdown can give pulse-by-pulse current limiting with a reset pulse from the clock output of the UC1524. R1C1 is used to filter leading edge spikes.

Figure 5. Current limiting.

APPLICATIONS

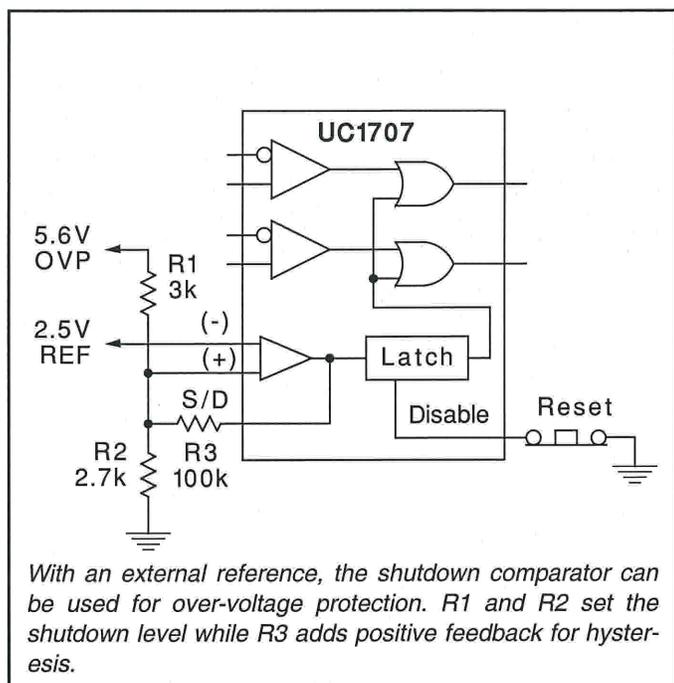


Figure 6. Over-voltage protection.

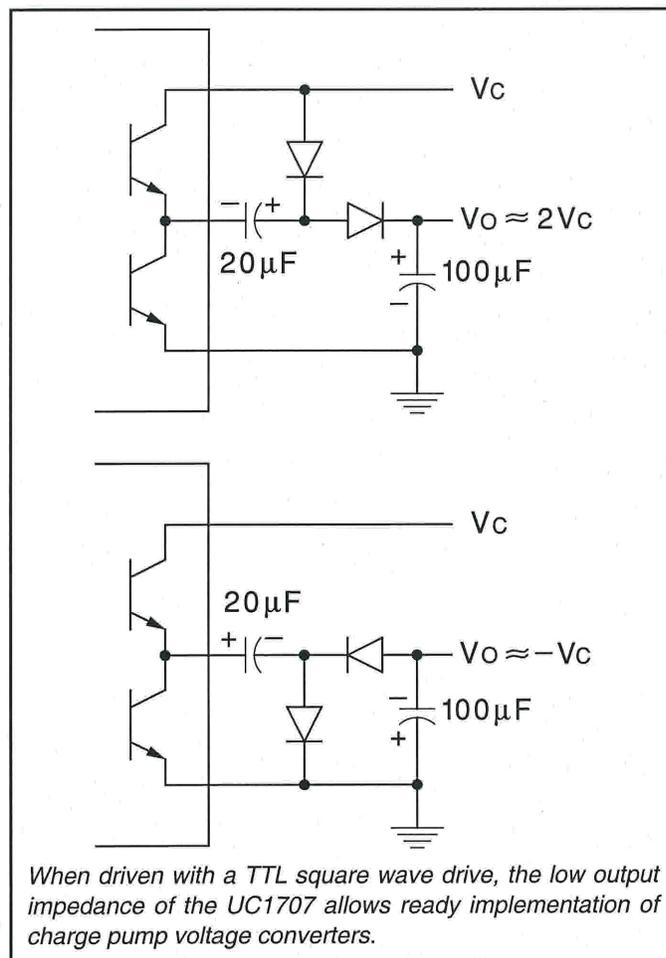


Figure 8. Charge pump circuits.

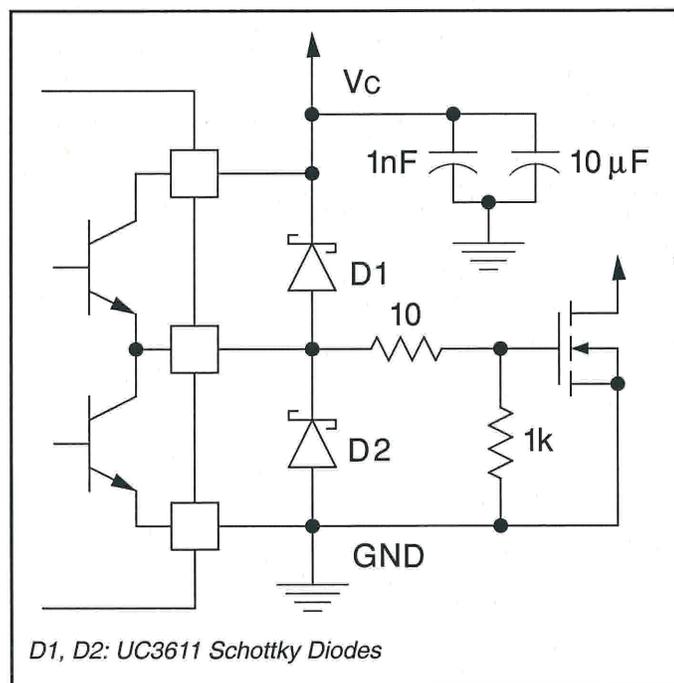


Figure 7. Power MOSFET drive circuit.

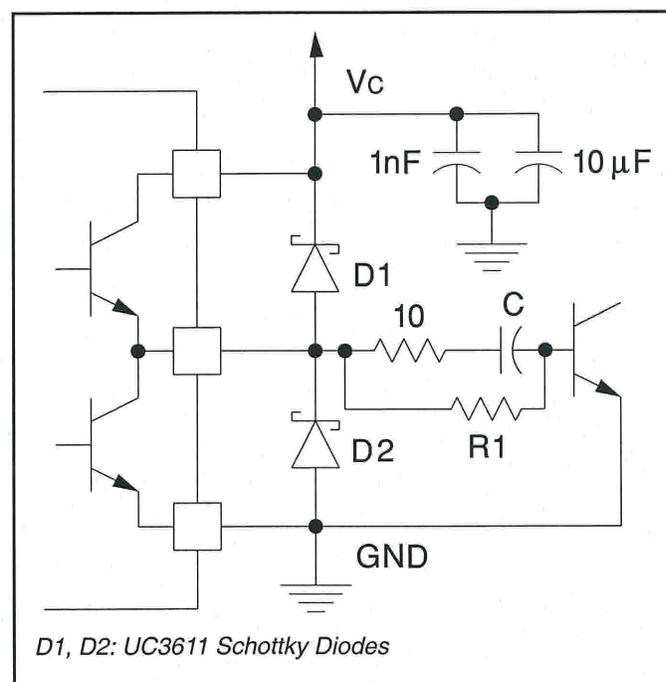


Figure 9. Power bipolar drive circuit.

TRANSFORMER COUPLING

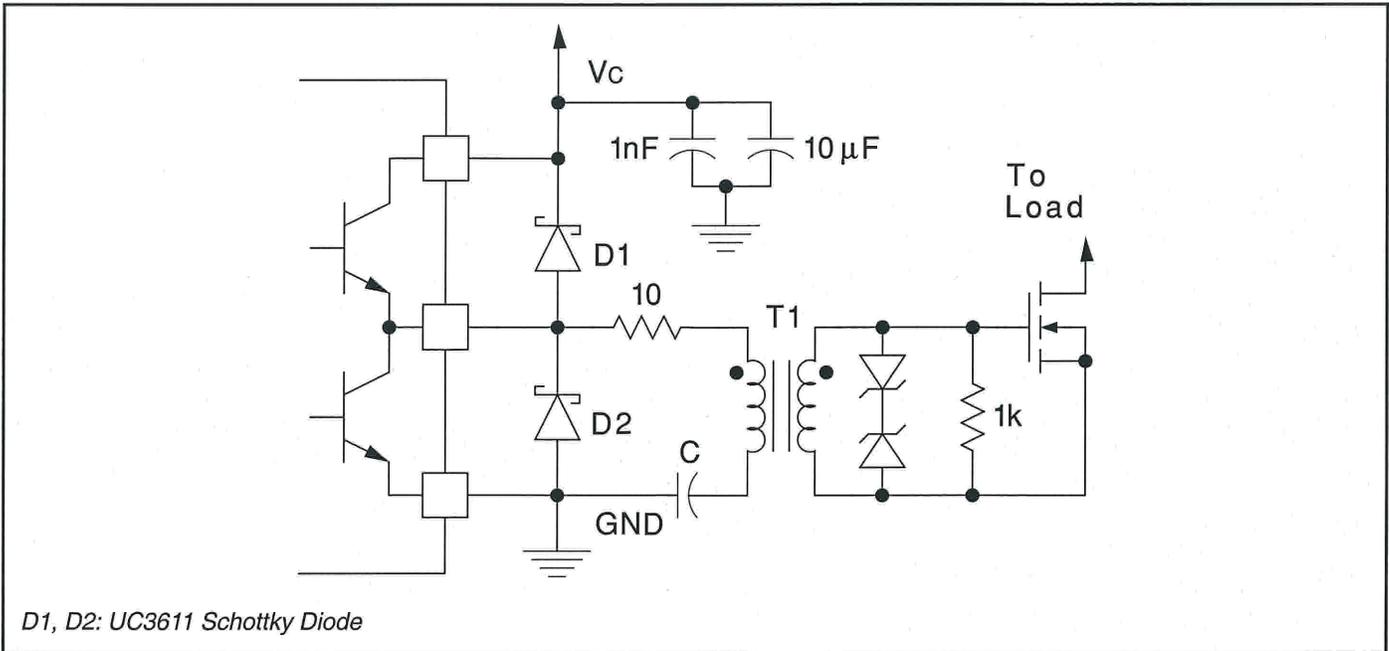


Figure 10. Transformer coupled MOSFET drive circuit.

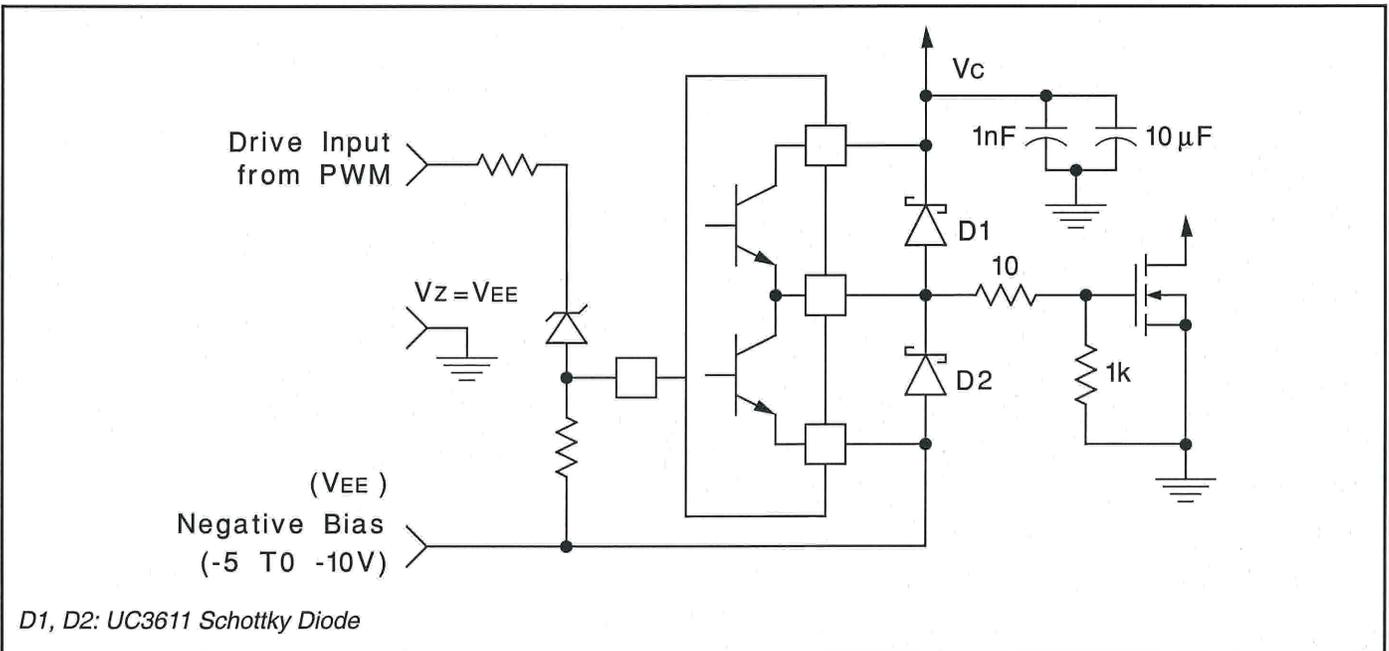


Figure 11. Power MOSFET drive circuit using negative bias voltage and level shifting to ground reference PWM.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87619012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8761901EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8761901V2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8761901VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
UC1707J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1707J/80313	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
UC1707J883B	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC1707JQMLV	ACTIVE	CDIP	J	16		TBD	Call TI	Call TI
UC1707L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC1707L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
UC2707DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2707DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2707DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2707DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2707N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2707NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2707Q	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC2707QG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC3707DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3707DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3707DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3707DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3707J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
UC3707N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3707NG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3707Q	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC3707QG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

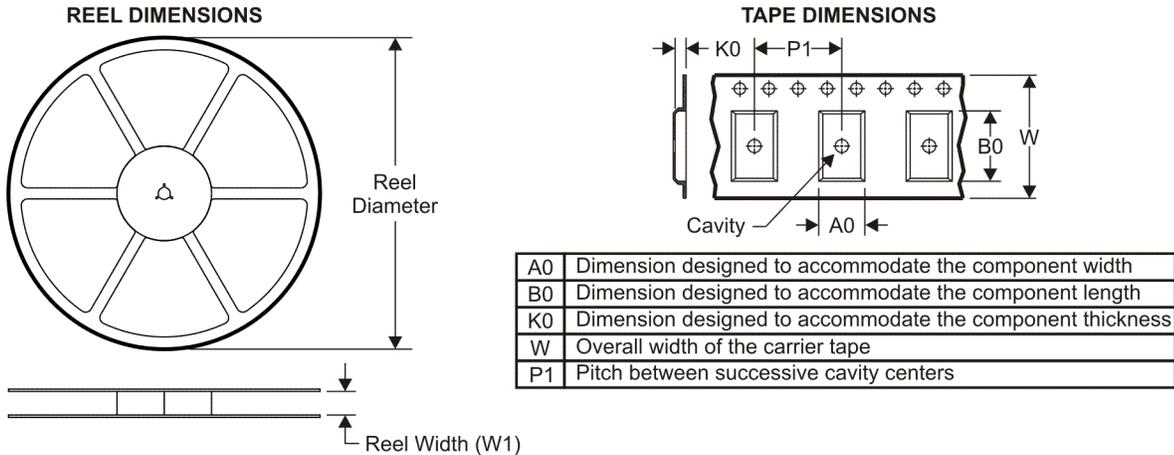
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

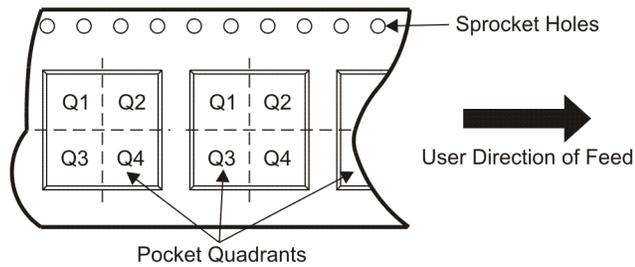
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TAPE AND REEL INFORMATION



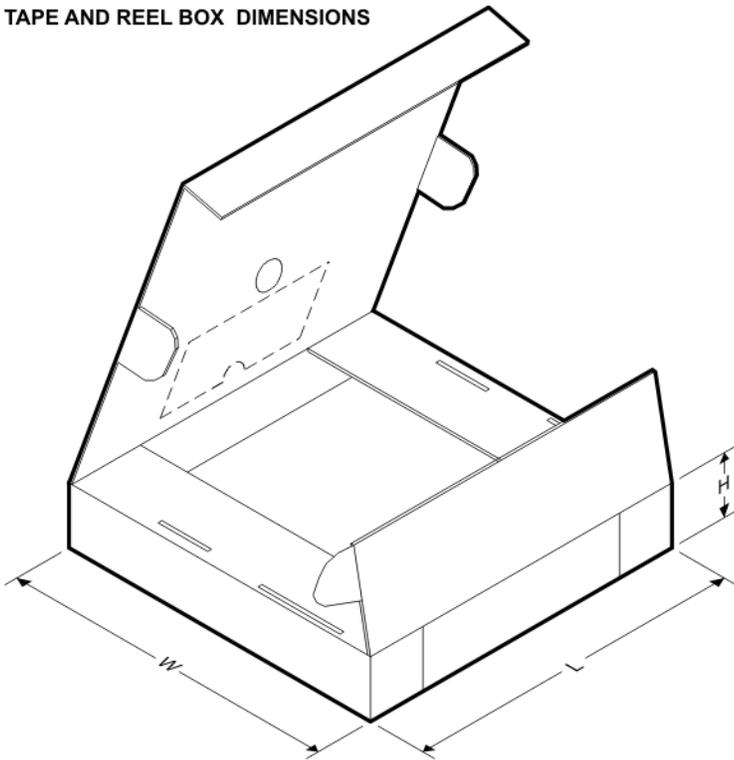
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2707DWTR	SOIC	DW	16	2000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1
UC3707DWTR	SOIC	DW	16	2000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2707DWTR	SOIC	DW	16	2000	346.0	346.0	33.0
UC3707DWTR	SOIC	DW	16	2000	346.0	346.0	33.0

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